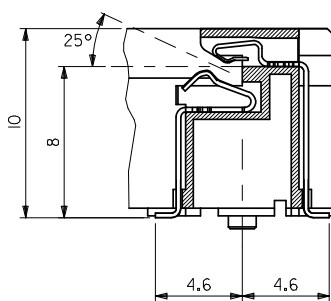
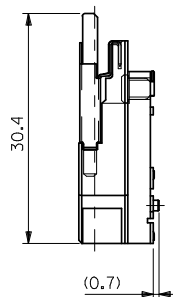


DETAIL C (SCALE:5-1)

DETAIL B (SCALE:5-1)

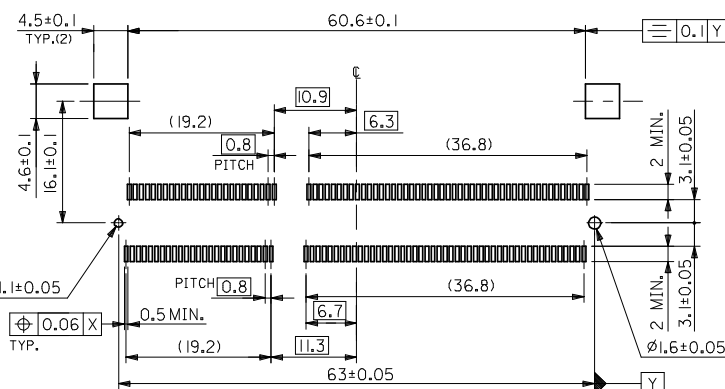


推奨基板寸法  
RECOMMENDED MATING BOARD CONFIGURATION  
(THK:1.0±0.1)

SECTION A-A  
(SCALE: 5-1)

注記 1. 材料 ハウジング : ガラス入りLCP、白色、UL94V-0  
HOUSING : G.F. LCP, WHITE, UL94V-0  
ターミナル : 燐青銅  
TERMINAL : PHOSPHOR BRONZE  
ネイル : 黄銅  
NAIL : BRASS  
ラッチカバー : ステンレス鋼  
LATCH COVER : STAINLESS STEEL

2. めっき仕様 ターミナル  
PLATING TERMINAL  
接点部 : 金めっき 0.25µmMIN.  
CONTACT AREA : GOLD 0.25 µmMIN.  
半田付け部 : 半田めっき 1.0µmMIN.  
SOLDER TAIL AREA : TIN-LEAD 1.0µmMIN.  
下地めっき : ニッケルめっき 2.0µmMIN.  
UNDER-PLATING : NICKEL 2.0µmMIN.  
ネイル  
NAIL  
半田めっき : 2.0µmMIN.  
TIN-LEAD : 2.0µmMIN.  
3. テール平坦度は、0.1 MAX.  
TAILS COPLANARITY TO BE 0.1 MAX.



推奨基板寸法  
RECOMMENDED PCB PATTERN LAYOUT  
(THK:1.2±0.1)

3.25	1.35	2.85	1.75	9.55	5.0V	標準トレイ NORMAL TRAY	54189-1441
E	D	C	B	A	POWER SUPPLY	確包トレイ PACKAGING TRAY	ENG.NO.
GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC
10 UNDER ±0.2				DRAWN BY M. YAGI		TITLE SGRA 0.8MM S.O DIMM HSG ASSY 144CKT (H=10)	
10 OVER 30 UNDER ±0.25				CHECKED BY Y ITO		THIRD ANGLE PROJECTION	
30 OVER ±0.3				APPROVED BY H IKESUGI		MOLEX INCORPORATED	
ANGULAR ±3 °				MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-54189-001	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A2		SHEET NO. 1 OF 1	